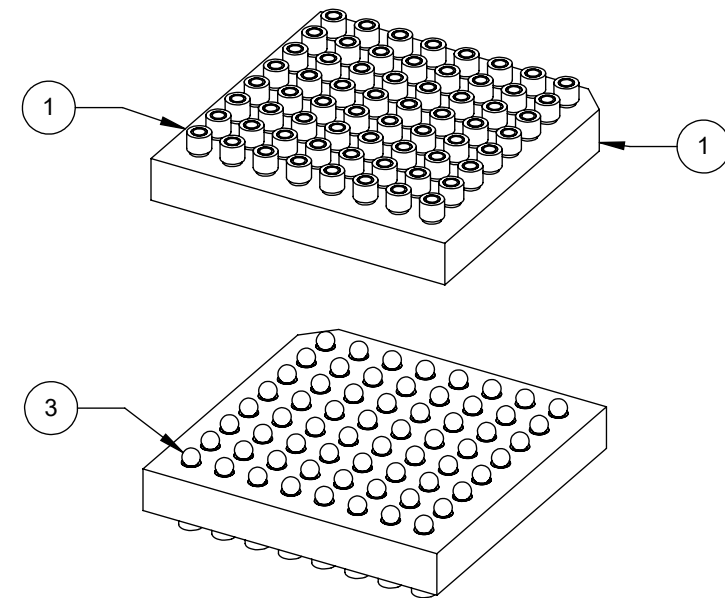
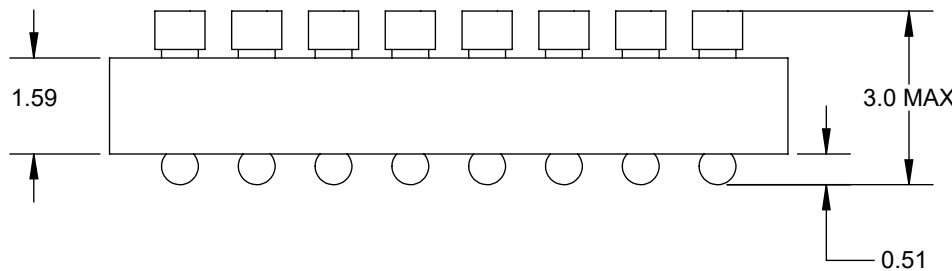
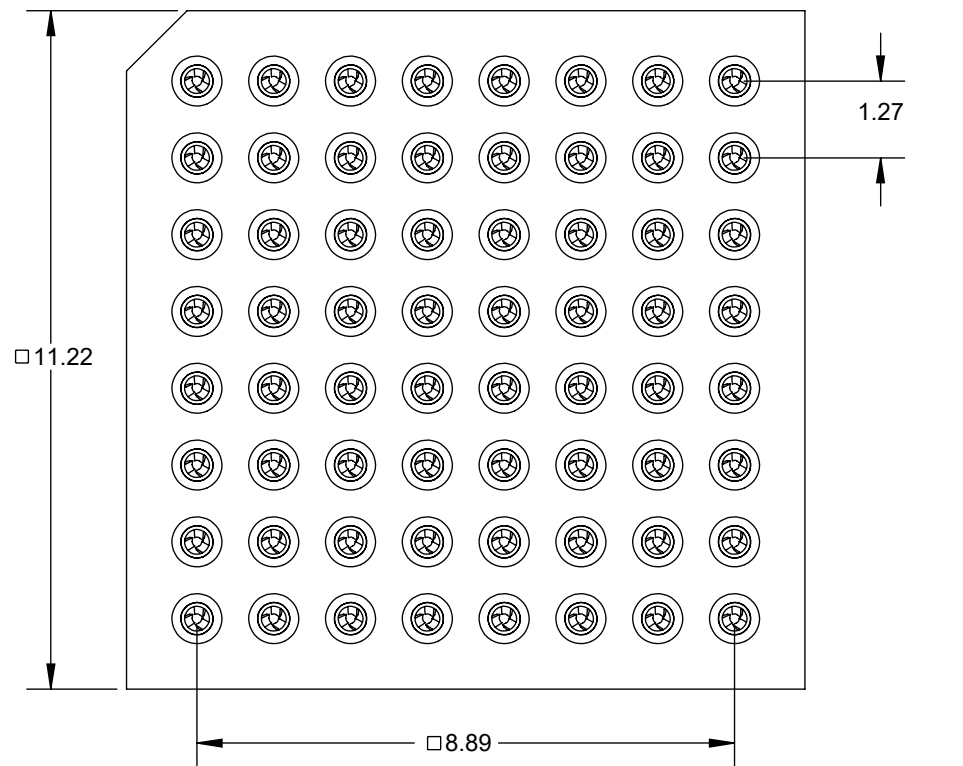


U.S. Patent No. 8,091,222 B2




ITEM NO.	DESCRIPTION
1	High Temp Substrate
2	Gold plated socket pin
3	Solder ball, $\varnothing 0.024$ " dia, Sn63 Pb37

NOTE: Packaged in 24mm carrier tape

Description: Female foot for 8x8 array 1.27mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ± 0.03 mm [± 0.001 "], Pitches (from true position) ± 0.025 mm [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

 SF-BGA64L-B-32 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: N/A	STATUS: Released	SHEET: 1 OF 1	REV. A
		ENG: B. Schatz	SCALE: 8:1	
		FILE: SF-BGA64L-B-32 Dwg	DATE: 09/18/2015	